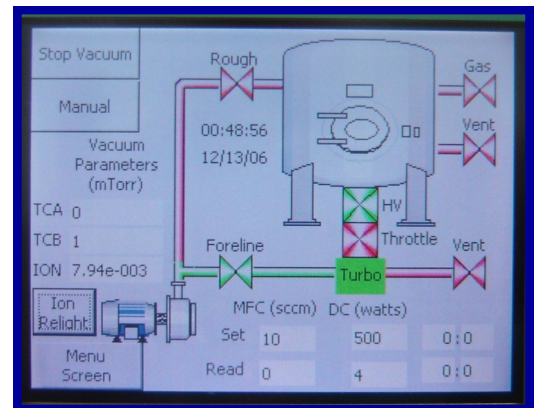


## Hummer® BC-24 Series

ONE SYSTEM IN A FAMILY OF PLANAR MAGNETRON SPUTTERING SYSTEMS

THIN FILM DEPOSITION OF METALS AND INSULATORS



### TOUCH-PANEL SYSTEM CONTROL

Vacuum and Process Control all in one.  
Functions are clearly displayed

QUARTZING  
CV DOT MATRIX  
FAILURE ANALYSIS  
MATERIALS RESEARCH  
MICROELECTRONICS RE-

BC Systems are available in sizes;  
16", 20", 24" and 30" D-style chambers  
(BC-20 chamber shown in photo)

The **HUMMER BC-24** sputter coater combines a high degree of process control and flexibility with ease of operation.

**THIN FILM RESEARCH - FAILURE ANALYSIS - PRODUCTION SUPPORT**

# HUMMER® BC-24

## PLANAR MAGNETRON SOURCE

### **TARGET DIAMETER -**

Two 4-inch round Standard,  
Optional - 2" & 3" diameter sources and Multiple sources

### **TARGET THICKNESS -**

1/16 to 1/4" standard

### **TARGET MATERIALS -**

Metals and / or insulators

### **SOURCE MOUNTING -**

Quick coupling to chamber, shutters, shields between sources as necessary

### **POWER SUPPLY -**

300 watts, 13.56 MHz. Standard  
Optional - 600, 1000 watts RF at 13.56 MHz.

1500 Watts DC Standard,  
Optional - 2500 Watts, or various combinations of supplies

### **COOLING WATER -**

.2 to 10 GPM required.  
Optional - Recirculation system

### **TARGET MOUNTING -**

## STAGE FIXTURE

**SIZE -** 2", 3", 4", 6", 8", 12" or 16"

**MOTION -** 360° rotation standard.

Optional - Variable angle of incidence to sputter source

**COOLING -** Optional

**REVERSE SPUTTER/ETCH -** Optional

**HEATED -** Optional to 900° C

## OVERALL SYSTEM

**CHAMBER -** 304 Stainless steel, 24" ID nominal, aluminum door, 4" Door view port, roughing, High Vacuum pump and instrument ports

**CONTROL -** Siemens S7-200 Series PLC control for each vacuum function and sputtering source. Fully integrated with easy "Touch-Panel" control pad for diagnostic and setting system parameters

**DESIGN -** Floor mount cabinet on casters with leveling pads

**SAFETY INTERLOCKS -** Water, power door and vacuum interlocks.

### **ELECTRICAL REQUIREMENTS -**

40-75 AMP, 208-240 Volt, 50/60 HZ

### **SPUTTERING -**

Standard Sputter down sputtering.  
Optional - Sputter-up or horizontal sputter

**AUTOMATIC SEQUENCING -** Standard

## IONIZATION SPECIES

### **GAS REQUIREMENTS -**

Argon regulated from 5 to 20 PSI

### **OPERATING PRESSURE -**

2 x 10<sup>-3</sup> to 5 x 10<sup>-2</sup>

### **REACTIVE SPECIES -**

Optional

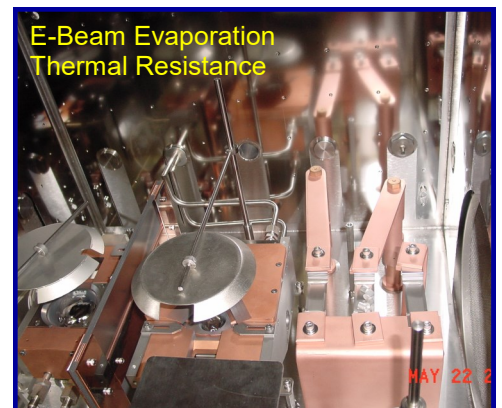
## VACUUM SYSTEM

**PUMPING -** Roughing pump and Turbo molecular pump - Standard  
Optional - Cryo pump or Larger pumps

**VACUUM GAUGING -** Convection gauges (2), Ion gauge (1). Atmosphere to 1 x 10<sup>-8</sup> TORR

**VALVES -** Electro-Pneumatic actuated High Vacuum/Throttle valve between pump and chamber. Fore-line and chamber roughing isolation valves. Pneumatic air or nitrogen (clean, dry) operating at 60-PSI.

**GAS CONTROL -** Mass Flow Controller (1) 100 sccm. Optional - Gases (3) maximum, for mixing and reactive gas sputtering



### **SOURCE OPTIONS**

Anatech USA offers alternatives for source configuration.  
Contact our sales staff.

## **CALL ANATECH USA TODAY TO DISCUSS YOUR APPLICATION**

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Sparks, NV 89431  
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